IN THE CLAIMS:

Please amend claims 1, 4, and 5, and add new claims 6-9 as follows:

LISTING OF CURRENT CLAIMS

- Claim 1. (Currently Amended) A high thermal conductive halogen-free phosphorus-free retardant resin composition comprising:
- (1) an epoxy resin, having bifunctional and polyfunctional groups, in an amount of 10 to 50% by weight of the total composition;
- (2) a retardant, having functional structure of amide, imide and hydroxy groups, in an amount of 10 to 30% by weight of the total composition, and having a chemical structure as (A):

wherein n is a positive integer;

- (3) an inorganic salt <u>powder</u>, in an amount of 10 to 50% by weight of the total composition; and
- (4) a high thermal conductive metal powder, in an amount of 10 to 30% by weight of the total composition.

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Claim 2. (Original) The high thermal conductive halogen-free phosphorusfree retardant resin composition as claimed in claim 1, wherein said epoxy resin has an epoxide equivalent of 150 to 1000.

Claim 3. (Original) The high thermal conductive halogen-free phosphorus-free retardant resin composition as claimed in claim 1, wherein said epoxy resin is selected depending on the application function from the group consisting of resins of diglycidyl ether type, resins of cresol novolac type, bisphenol A type resin (BPA) for improving the flow property of the resin, styrene-maleic-anhydride resin (SMA) exhibiting high reliability and low hygroscopicity and heat resistance, and functional resin of poly-phenylene ether (PPE) capable of providing low dielectric constant.

Claim 4. (Currently Amended) The high thermal conductive halogen-free phosphorus-free retardant resin composition as claimed in claim 1, wherein said inorganic powder is selected from the group consisting of silicon dioxide, titanitum titanium dioxide, alumina, aluminum hydroxide, magnesium hydroxide, calcium carbonate and mixtures thereof having an average particle size between 0.01 micron and 5 micron.

Claim 5. (Currently Amended) The high thermal conductive halogen-free phosphorus-free retardant resin composition as claimed in claim 1, wherein said high thermal conductive <u>metal</u> powder is selected from the group consisting of aluminum nitride, boron nitride, aluminum oxide, silver, aluminum, zinc oxide, carbon nano tube (CNT) and <u>mixture mixtures</u> thereof having a <u>an</u> average particle size is between 0.01 micron and 10 micron.

Claim 6. (New) The high thermal conductive halogen-free phosphorus-free retardant resin composition as claimed in claim 1, wherein said high thermal conductive metal powder is selected from the group consisting of aluminum nitride, boron nitride, silver, aluminum, zinc oxide, carbon nano tube (CNT) and mixtures thereof having an average particle size between 0.01 micron and 10 micron.

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Claim 7. (New) The high thermal conductive halogen-free phosphorus-free retardant resin composition as claimed in claim 1, wherein said inorganic powder is selected from the group consisting of titanium dioxide, aluminum hydroxide, magnesium hydroxide, calcium carbonate and mixtures thereof having an average particle size between 0.01 micron and 5 micron.

Claim 8. (New) The high thermal conductive halogen-free phosphorus-free retardant resin composition as claimed in claim 7, wherein said high thermal conductive metal powder is selected from the group consisting of aluminum nitride, boron nitride, silver, aluminum, zinc oxide, carbon nano tube (CNT) and mixtures thereof having an average particle size between 0.01 micron and 10 micron.

Claim 9. (New) A high thermal conductive halogen-free phosphorus-free retardant resin composition comprising:

- (1) an epoxy resin, having bifunctional and polyfunctional groups, in an amount of 10 50% by weight of the total composition;
- (2) a retardant, having functional structure of amide, imide and hydroxy groups, in an amount of 10 30% by weight of the total composition, and having a chemical structure as (A):

$$||0-C|| = \frac{1}{C}$$

$$||0-C||$$

wherein n is a positive integer;

(3) an inorganic powder, in an amount of 10 - 50% by weight of the total composition wherein said inorganic powder has an average particle size of 0.01

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micron - 5 micron and comprises titanium dioxide, aluminum hydroxide, magnesium hydroxide, calcium carbonate or a mixture thereof; and

(4) a high thermal conductive metal powder, in an amount of 10 - 30% by weight of the total composition wherein said high thermal conductive metal powder has an average particle size of 0.01 micron - 10 micron and comprises aluminum nitride, boron nitride, silver, aluminum, zinc oxide, a carbon nano tube or a mixture thereof.